

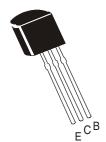
Continental Device India Limited

An ISO/TS 16949, ISO 9001 and ISO 14001 Certified Company





SILICON PLANAR EPITAXIAL TRANSISTORS



CLB764 PNP CLD863 NPN

TO-92 Plastic Package

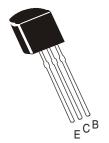
Voltage Regulator, Relay Lamp Driver Electrical Equipment Applications

ABSOLUTE MAXIMUM RATINGS ($T_a=25^{\circ}C$)

DESCRIPTION	SYMBOL	VALUE	UNITS
Collector Base Voltage	V_{CBO}	60	V
Collector Emitter Voltage	V_{CEO}	50	V
Emitter Base Voltage	V_{EBO}	5.0	V
Collector Current	I _C	1.0	Α
Peak Collector Current	I _{CP}	2.0	А
Collector Power Dissipation	P _C	0.9	W
Junction Temperature	T _j	150	ōC
Storage Temperature	T_{stg}	- 55 to +150	ōС

ELECTRICAL CHARACTERISTICS (T _a =25°C unless specified otherwise)								
DESCRIPTION	SYMBOL	TEST CONDITION	MIN	MAX	UNITS			
Collector Base Voltage	V _{CBO}	I _C =10μA, I _E =0	60		V			
Collector Emitter Voltage	V _{CEO}	I _C =1mA, I _B =0	50		V			
Emitter Base Voltage	V_{EBO}	I _E =10μA, I _C =0	5.0		V			
Collector Cut Off Current	I _{CBO}	$V_{CB}=50V, I_{E}=0$		1.0	μΑ			
Emitter Cut Off Current	I _{EBO}	$V_{EB}=4V, I_{C}=0$		1.0	μΑ			
DC Current Gain	*h _{FE}	I _C =50mA, V _{CE} =2V	60	320				
	h _{FE}	I _C =1A, V _{CE} =2V	30					
Collector Emitter Saturation Voltage	V _{CE (sat)}	I _C =500mA, I _B =50mA						
		NPN		0.5	V			
		PNP		0.7	V			
Base Emitter Saturation Voltage	V _{BE (sat)}	$I_C=500$ mA, $I_B=50$ mA		1.2	V			

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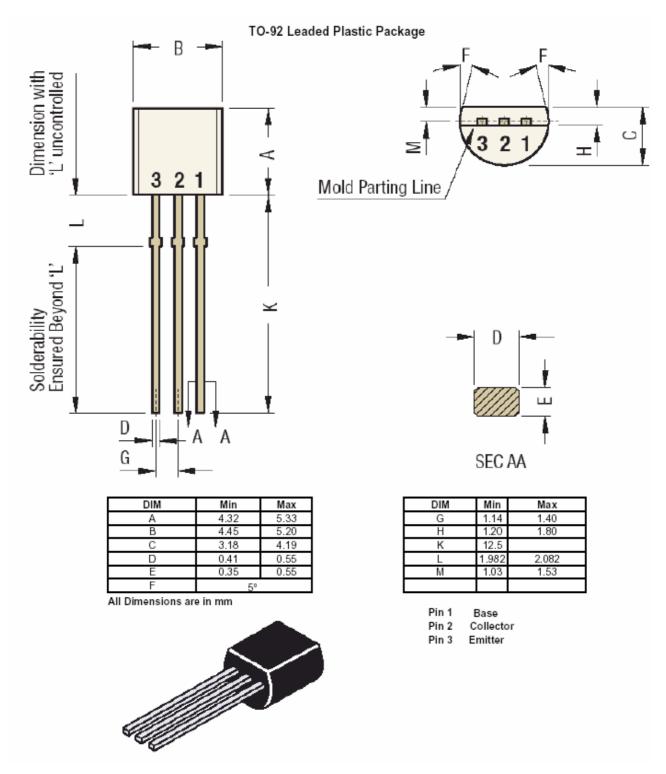
DYNAMIC CHARACTERISTICS

Transition Frequency	f _T	V _{CE} =10V, I _C =50mA	TYP150	MHz
Output Capacitance	C_ob	$V_{CB}=10V, I_{E}=0, f=1MHz$		
		NPN	TYP12	pF
		PNP	TYP20	pF

CLASSIFICATION	D	Е	F
*h _{FE}	60 - 120	100 - 200	160 - 320

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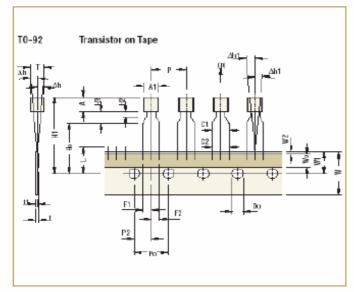
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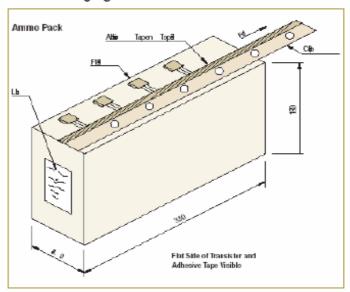


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TO-92 Plastic Package

TO-92 Tape and Ammo Packaging





All Dimensions are in mm

Tape Specifications

Item description	Symbol
Body width	A1
Body height	А
Body thickness	Т
Pitch of component ^{Cr}	P
Feed hole pitch ^{§1}	Po
Feed hole center to	
component centre52	P2
Comp. alignment, Side view ^{§3}	Dh
Comp. alignment, Front view ^{§3}	Dh1
Tape width ^{Cr}	W
Hold down tape width ^{Cr}	Wo
Hole position	W1
Hold-down tape position	W2
Lead wire clinch height	Ho
Component height	H1
Length of snipped leads	L
Feed hole diameter ^{cr}	Do
Total tape thickness ^{§4}	t
Lead-to-lead distance ^{Cr}	F1, F2
Stand off	H2
Clinch height	Н3
Lead parallelismCr	C1-C2
Pull-out force	(p)

Min	Nom	Max	Tol
4.45		5.20	
4.32		5.33	
3.18		4.19	
	12.7		±1.0
	12.7		±0.3
	6.35		±0.4
	0	1.0	
	0	1.3	
	18		±0.5
	6		±0.2
	9		+0.7 -0.5
0.0		0.7	
	16		±0.5
		24.0	
		11.0	
	4		±0.2
		1.2	
2.4		2.7	
0.45		1.45	
		3.0	
		0.22	
6N			

Taping Specification

- Maximum alignment deviation between leads not to be greater than 0.20 mm.
- Maximum non-cumulative variation between tape feed holes shall not exceed 1 mm in 20 pitches.
- Hold down tape not to exceed beyond the edge(s) carrier tape and there shall be no exposure of adhesive.
- No more than 3 consecutive missing components is permitted.
- A tape trailer, having at least three feed holes is required after the last component.
- Splices shall not interfere with the sprocket feed holes.
- §1 Cumulative pitch error 1.0 mm/20 pitch.
- §2 To be measured at bottom of clinch.
- §3 At top of body.
- $\S4 ext{ } t1 = 0.3 0.6 ext{ mm}$
- Cr Critical Dimension.

All Dimensions are in mm

TO-92
Plastic Package

Packaging Information

T & A: Tape and Ammo Pack; T & R: Tape and Red; Bulk: Loose in Poly bags; Tube: Tube and Ammo Pack; k: 1.000

Package/Case		Std. Packing		Inner Carton			Outer Carton		
-	Packaging Type	Qty	Qty	Size L x W x H	Gross Weight	Qty	Size L x W x H	Gross Weight	
Type	Qty	Qty	(cm)	(Kg)	Giy	(cm)	(Kg)		
TO-92	Bulk	1,000	5K	19x19x8	1.10	80K	43x40x35	20.0	
10-92	T&A	2,000	2K	32x4.5x20	0.70	40K	43x40x35	15.20	

Component Disposal Instructions

- 1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

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